64K (8K x 8)

E<sup>2</sup>PROM with

Page Write and

**Software Data** 

**Protection** 

**CMOS** 

#### **Features**

- Fast Read Access Time 150 ns
- Automatic Page Write Operation

Internal Address and Data Latches for 64-Bytes

• Fast Write Cycle Times

Page Write Cycle Time: 10 ms Maximum 1 to 64-Byte Page Write Operation

Low Power Dissipation

40 mA Active Current

100 μA CMOS Standby Current

- Hardware and Software Data Protection
- DATA Polling and Toggle Bit for End of Write Detection

 High Reliability CMOS Technology Endurance: 100,000 Cycles Data Retention: 10 Years

- Single 5V ± 10% Supply
- CMOS and TTL Compatible Inputs and Outputs
- JEDEC Approved Byte-Wide Pinout
- Commercial and Industrial Temperature Ranges

#### Description

The AT28C64B is a high-performance electrically erasable and programmable read only memory (EEPROM). Its 64K of memory is organized as 8,192 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 150 ns with power dissipation of just 220 mW. When the device is deselected, the CMOS standby current is less than 100  $\mu$ A.

(continued)

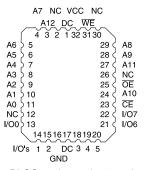
### **Pin Configurations**

Pin Name	Function
A0 - A12	Addresses
CE	Chip Enable
ŌE	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect
DC	Don't Connect

PDIP, SOIC Top View

	ſ		$\neg$		1	
NC	$\Box$	1		28	Þ	VCC
A12		2		27	Þ	WE
Α7	□	3		26	Þ	NC
A6		4		25		A8
A5		5		24	Þ	Α9
A4	d	6		23	Þ	A11
А3		7		22	Þ	ŌĒ
A2		8		21	Þ	A10
A1	d	9		20	Þ	CE
A0		10		19	Þ	1/07
I/O0	$\Box$	11		18	Þ	1/06
I/O1		12		17	þ	1/05
1/02		13		16	Þ	1/04
GND	$\Box$	14		15	þ	1/03
					ı	

#### PLCC Top View



TSOP Top View

							_		
A11	OE F	Г	2	1	28	27	È	A10	CE
	A9 🗏			3	26		Ē	<b>I</b> /O7	
A8	NC =		4	5	24	25	Ĕ	I/O5	I/O6
WE	vcc =	L	6	7	22	23	Ė	1/03	I/O4
NC		ν	8	-		21	Ē		GND
Α7	A12 =		10	9	20	19	Б	I/O2	I/O1
	A6 ⊑	1		11	18		Þ	I/O0	
A5	A4 🗀		12	13	16	17	Ĕ	A1	A0
АЗ		1	14			15	Р		A2

Note: PLCC package pins 1 and 17 are DON'T CONNECT.

0270E



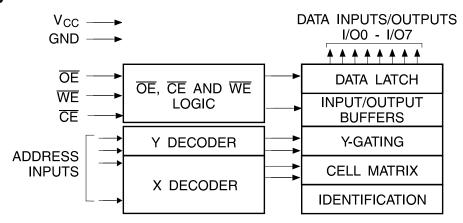


#### **Description** (Continued)

The AT28C64B is accessed like a Static RAM for the read or write cycle without the need for external components. The device contains a 64-byte page register to allow writing of up to 64-bytes simultaneously. During a write cycle, the addresses and 1 to 64-bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a write cycle, the device will automatically write the latched data using an internal control timer. The end of a write cycle can be detected by DATA POLLING of I/O7. Once the end of a write cycle has been detected, a new access for a read or write can begin.

Atmel's AT28C64B has additional features to ensure high quality and manufacturability. The device utilizes internal error correction for extended endurance and improved data retention characteristics. An optional software data protection mechanism is available to guard against inadvertent writes. The device also includes an extra 64-bytes of E<sup>2</sup>PROM for device identification or tracking.

#### **Block Diagram**



#### **Absolute Maximum Ratings\***

Temperature Under Bias55°C to +125°C
Storage Temperature65°C to +150°C
All Input Voltages (including NC Pins) with Respect to Ground0.6V to +6.25V
All Output Voltages with Respect to Ground0.6V to V <sub>CC</sub> + 0.6V
Voltage on $\overline{\text{OE}}$ and A9 with Respect to Ground0.6V to +13.5V

\*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **Device Operation**

**READ:** The AT28C64B is accessed like a Static RAM. When CE and OE are low and WE is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The <u>outputs</u> are put in the high-impedance state when either CE or OE is high. This dual line control gives designers flexibility in preventing bus contention in their systems.

BYTE WRITE: A low pulse on the WE or CE input with CE or WE low (respectively) and OE high initiates a write cycle. The address is latched on the falling edge of CE or WE, whichever occurs last. The data is latched by the first rising edge of CE or WE. Once a byte write has been started, it will automatically time itself to completion. Once a programming operation has been initiated and for the duration of two, a read operation will effectively be a polling operation.

**PAGE WRITE:** The page write operation of the AT28C64B allows 1 to 64-bytes of data to be written into the device during a single internal programming period. A page write operation is initiated in the same manner as a byte write; after the first byte is written, it can then be followed by 1 to 63 additional bytes. Each successive byte must be loaded within 150  $\mu$ s (tBLC) of the previous byte. If the tBLC limit is exceeded, the AT28C64B will cease accepting data and commence the internal programming operation. All bytes during a page write operation must reside on the same page as defined by the state of the A6 to A12 inputs. For each WE high to low transition during the page write operation, A6 to A12 must be the same.

The A0 to A5 inputs specify which bytes within the page are to be written. The bytes may be loaded in any order and may be altered within the same load period. Only bytes which are specified for writing will be written; unnecessary cycling of other bytes within the page does not occur.

**DATA POLLING:** The AT28C64B features DATA Polling to indicate the end of a write cycle. During a byte or page write cycle an attempted read of the last byte written will result in the complement of the written data to be presented on I/O7. Once the write cycle has been completed, true data is <u>valid</u> on all outputs, and the next write cycle may begin. DATA Polling may begin at any time during the write cycle.

**TOGGLE BIT:** In addition to DATA Polling, the AT28C64B provides another method for determining the end of a write cycle. During the write operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the write has completed, I/O6 will stop toggling, and valid data will be read. Toggle bit reading may begin at any time during the write cycle.

**DATA PROTECTION:** If precautions are not taken, inadvertent writes may occur during transitions of the host system power supply. Atmel has incorporated both hardware and software features that will protect the memory against inadvertent writes.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent writes to the AT28C64B in the following ways: (a) VCC sense - if VCC is below 3.8V (typical), the write function is inhibited; (b) VCC power-on delay - once VCC has reached 3.8V, the device will automatically time out 5 ms (typical) before allowing a write; (c) write inhibit - holding any one of OE low, CE high, or WE high inhibits write cycles; (d) noise filter - pulses of less than 15 ns (typical) on the WE or CE inputs will not initiate a write cycle.

**SOFTWARE DATA PROTECTION:** A software controlled data protection feature has been implemented on the AT28C64B. When enabled, the software data protection (SDP), will prevent inadvertent writes. The SDP feature may be enabled or disabled by the user; the AT28C64B is shipped from Atmel with SDP disabled.

SDP is enabled by the user issuing a series of three write commands in which three specific bytes of data are written to three specific addresses (refer to the *Software Data Protection Algorithm* diagram in this data sheet). After writing the 3-byte command sequence and waiting two, the entire AT28C64B will be protected against inadvertent writes. It should be noted that even after SDP is enabled, the user may still perform a byte or page write to the AT28C64B by preceding the data to be written by the same 3-byte command sequence used to enable SDP.

Once set, SDP remains active unless the disable command sequence is issued. Power transitions do not disable SDP, and SDP protects the AT28C64B during power-up and power-down conditions. All command sequences must conform to the page write timing specifications. The data in the enable and disable command sequences is not actually written into the device; their addresses may still be written with user data in either a byte or page write operation.

After setting SDP, any attempt to write to the device without the 3-byte command sequence will start the internal write timers. No data will be written to the device. However, for the duration of  $t_{WC}$ , read operations will effectively be polling operations.

**DEVICE IDENTIFICATION:** An extra 64-bytes of EEPROM memory are available to the user for device identification. By raising A9 to 12V  $\pm$  0.5V and using address locations 1FC0H to 1FFFH, the additional bytes may be written to or read from in the same manner as the regular memory array.





## **DC and AC Operating Range**

		AT28C64B-15	AT28C64B-20	AT28C64B-25
Operating	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C
Temperature (Case)	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
Vcc Power Supply		5V ± 10%	5V ± 10%	5V ± 10%

## **Operating Modes**

Mode	CE	ŌĒ	WE	I/O	
Read	VIL	VIL	VIH	Douт	
Write (2)	V <sub>IL</sub>	V <sub>IH</sub>	VIL	D <sub>IN</sub>	
Standby/Write Inhibit	ViH	X <sup>(1)</sup>	Х	High Z	
Write Inhibit	Х	Х	VIH		
Write Inhibit	Χ	VIL	Χ		
Output Disable	Х	Vih	Х	High Z	
Chip Erase	V <sub>IL</sub>	V <sub>H</sub> <sup>(3)</sup>	VIL	High Z	

Notes: 1. X can be V<sub>IL</sub> or V<sub>IH</sub>.

3.  $V_H = 12.0V \pm 0.5V$ .

#### **DC Characteristics**

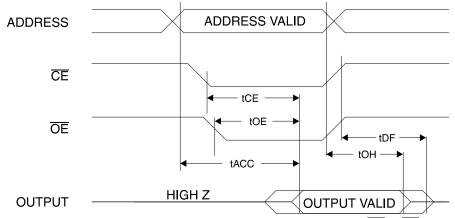
Symbol	Parameter	Condition	Min	Max	Units
I <sub>LI</sub>	Input Load Current	$V_{IN} = 0V$ to $V_{CC} + 1V$		10	μΑ
ILO	Output Leakage Current	$V_{I/O} = 0V$ to $V_{CC}$		10	μΑ
I <sub>SB1</sub>	V <sub>CC</sub> Standby Current CMOS	$\overline{\text{CE}} = \text{V}_{\text{CC}} - 0.3 \text{V to V}_{\text{CC}} + 1 \text{V}$ Com.	, Ind.	100	μΑ
I <sub>SB2</sub>	V <sub>CC</sub> Standby Current TTL	$\overline{\text{CE}}$ = 2.0V to V <sub>CC</sub> + 1V		2	mA
Icc	Vcc Active Current	f = 5 MHz; I <sub>OUT</sub> = 0 mA		40	mA
VIL	Input Low Voltage			8.0	<b>V</b>
VIH	Input High Voltage		2.0		V
VoL	Output Low Voltage	I <sub>OL</sub> = 2.1 mA		.40	<b>V</b>
Vон	Output High Voltage	I <sub>OH</sub> = -400 μA	2.4		V

<sup>2.</sup> Refer to the *AC Write Waveforms* diagrams in this data sheet.

#### **AC Read Characteristics**

		AT28C64B-15 AT28C64B-20		C64B-20	AT28C64B-2			
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Units
tACC	Address to Output Delay		150		200		250	ns
t <sub>CE</sub> <sup>(1)</sup>	CE to Output Delay		150		200		250	ns
toE (2)	OE to Output Delay	0	70	0	80	0	100	ns
t <sub>DF</sub> (3, 4)	CE or OE to Output Float	0	50	0	55	0	60	ns
tон	Output Hold from OE, CE or Address, whichever occurred first	0		0		0		ns

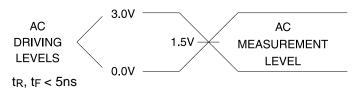
## **AC Read Waveforms** (1, 2, 3, 4)



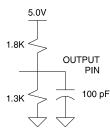
Notes: 1.  $\overline{\text{CE}}$  may be delayed up to t<sub>ACC</sub> - t<sub>CE</sub> after the address transition without impact on t<sub>ACC</sub>.

- OE may be delayed up to t<sub>CE</sub> t<sub>OE</sub> after the falling edge of CE without impact on t<sub>CE</sub> or by t<sub>ACC</sub> - t<sub>OE</sub> after an address change without impact on t<sub>ACC</sub>.
- 3.  $t_{DF}$  is specified from  $\overline{OE}$  or  $\overline{CE}$  whichever occurs first  $(C_L = 5 \text{ pF})$ .
- 4. This parameter is characterized and is not 100% tested.

# Input Test Waveforms and Measurement Level



## **Output Test Load**



## Pin Capacitance (f = 1 MHz, T = $25^{\circ}$ C) (1)

	Тур	Max	Units	Conditions
C <sub>IN</sub>	4	6	pF	$V_{IN} = 0V$
Соит	8	12	pF	$V_{OUT} = 0V$

Note: 1. This parameter is characterized and is not 100% tested.



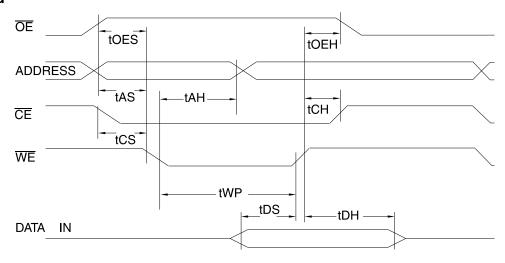


#### **AC Write Characteristics**

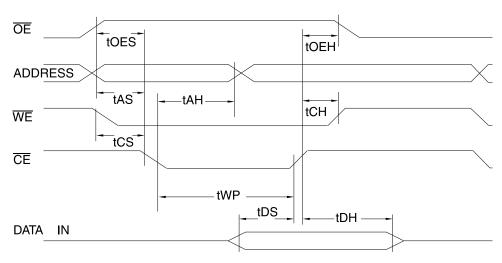
Symbol	Parameter	Min	Max	Units
tas, toes	Address, OE Set-up Time	0		ns
tah	Address Hold Time	50		ns
tcs	Chip Select Set-up Time	0		ns
tch	Chip Select Hold Time	0		ns
twp	Write Pulse Width (WE or CE)	100		ns
tos	Data Set-up Time	50		ns
t <sub>DH</sub> , t <sub>OEH</sub>	Data, OE Hold Time	0		ns

#### **AC Write Waveforms**

#### **WE** Controlled



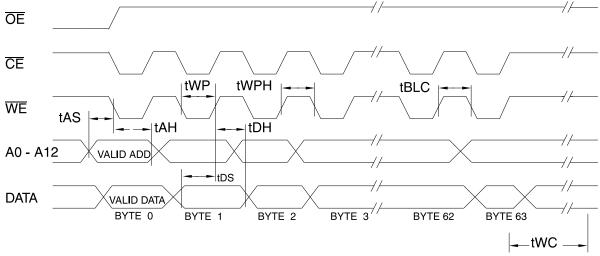
#### **CE** Controlled



### **Page Mode Characteristics**

Symbol	Parameter	Min	Max	Units
twc	Write Cycle Time		10	ms
tas	Address Set-up Time	0		ns
t <sub>AH</sub>	Address Hold Time	50		ns
tDS	Data Set-up Time	50		ns
t <sub>DH</sub>	Data Hold Time	0		ns
twp	Write Pulse Width	100		ns
t <sub>BLC</sub>	Byte Load Cycle Time		150	μs
twph	Write Pulse Width High	50		ns

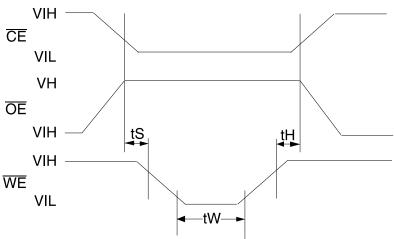
# Page Mode Write Waveforms (1, 2)



Notes: 1.  $\underline{A6}$  through A12 must specify the same page address during each high to low transition of  $\overline{\text{WE}}$  (or  $\overline{\text{CE}}$ ).

2. OE must be high only when WE and CE are both low.

### **Chip Erase Waveforms**

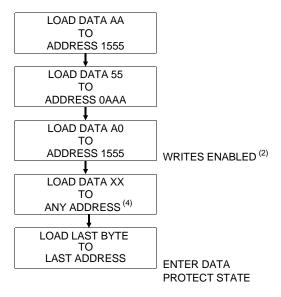


 $t_S = t_H = 5 \mu sec (min.)$   $t_W = 10 msec (min.)$  $V_H = 12.0V \pm 0.5V$ 





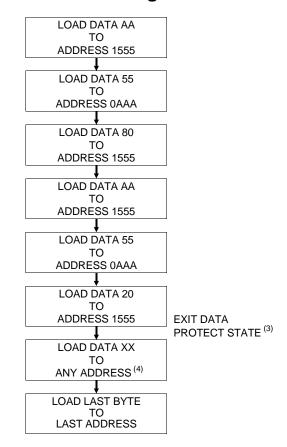
# Software Data Protection Enable Algorithm (1)



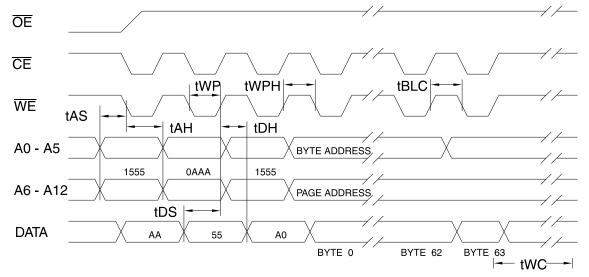
Notes for software program code:

- 1. Data Format: I/O7 I/O0 (Hex); Address Format: A12 - A0 (Hex).
- Write Protect state will be activated at end of write even if no other data is loaded.
- 3. Write Protect state will be deactivated at end of write period even if no other data is loaded.
- 4. 1 to 64-bytes of data are loaded.

# Software Data Protection Disable Algorithm (1)



## **Software Protected Write Cycle Waveforms** (1, 2)



Notes: 1. A6 through A12 must specify the same page address during each high to low transition of WE (or CE) after the software code has been entered.

2.  $\overline{OE}$  must be high only when  $\overline{WE}$  and  $\overline{CE}$  are both low.

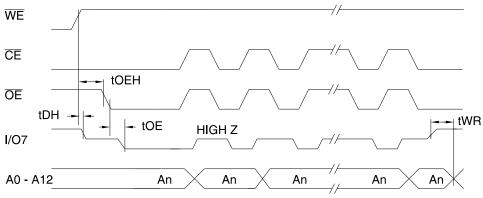
## **Data Polling Characteristics** (1)

Symbol	Parameter	Min	Тур	Max	Units
t <sub>DH</sub>	Data Hold Time	0			ns
toeh	OE Hold Time	0			ns
toE	OE to Output Delay (2)				ns
twR	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See AC Read Characteristics.

#### **Data Polling Waveforms**



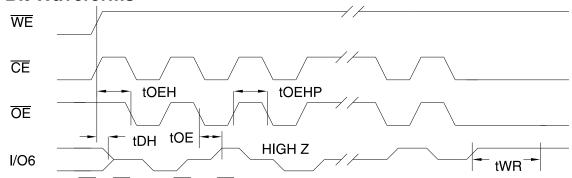
## Toggle Bit Characteristics (1)

Symbol	Parameter	Min	Тур	Max	Units
tDH	Data Hold Time	10			ns
toeh	OE Hold Time	10			ns
toE	OE to Output Delay (2)				ns
toehp	OE High Pulse	150			ns
twR	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See AC Read Characteristics.

## **Toggle Bit Waveforms** (1, 2, 3)



Notes: 1. Toggling either  $\overline{OE}$  or  $\overline{CE}$  or both  $\overline{OE}$  and  $\overline{CE}$  will operate toggle bit.

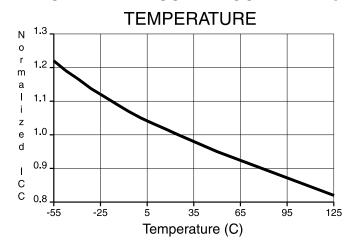
2. Beginning and ending state of I/O6 will vary.

3. Any address location may be used but the address should not vary.

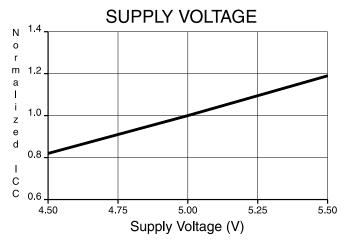




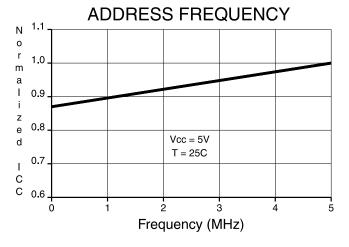
#### NORMALIZED SUPPLY CURRENT vs.



#### NORMALIZED SUPPLY CURRENT vs.



#### NORMALIZED SUPPLY CURRENT vs.



## **Ordering Information** (1)

tACC	Icc	(mA)	Ordering Code	D I	Operation Range
(ns)	Active	Standby		Package	
150	40	0.1	AT28C64B-15JC AT28C64B-15PC AT28C64B-15SC AT28C64B-15TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
			AT28C64B-15JI AT28C64B-15PI AT28C64B-15SI AT28C64B-15TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
200	40	0.1	AT28C64B-20JC AT28C64B-20PC AT28C64B-20SC AT28C64B-20TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
			AT28C64B-20JI AT28C64B-20PI AT28C64B-20SI AT28C64B-20TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
250	40	0.1	AT28C64B-25JC AT28C64B-25PC AT28C64B-25SC AT28C64B-25TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
			AT28C64B-25JI AT28C64B-25PI AT28C64B-25SI AT28C64B-25TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
	40	0.1	AT28C64B-W	DIE	Commercial (0°C to 70°C)

Note: 1. See Valid Part Number table below.

#### **Valid Part Numbers**

The following table lists standard Atmel products that can be ordered.

Device Numbers	Speed	Package and Temperature Combinations
AT28C64B	15	JC, JI, PC, PI, SC, SI, TC, TI
AT28C64B	20	JC, JI, PC, PI, SC, SI, TC, TI
AT28C64B	25	JC, JI, PC, PI, SC, SI, TC, TI
AT28C64B	-	W





Package Type				
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)			
28P6	28 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)			
28\$	28 Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)			
28T	28 Lead, Plastic Thin Small Outline Package (TSOP)			
W	DIE			